3D Packaging and Integration Japan TC Chapter

Japan Standards Winter 2021 Meetings

Monday, January 18, 2021,

SEMI Japan office, Tokyo, Japan

14:00-17:30

AGENDA Draft

1 Welcome / Call to Order

1.1 Introductions

1.2 Meeting Reminders (Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines)

1.3 Agenda Review

2 Review of Previous Meeting of 3D Packaging & Integration Japan TC Chapter

3 Liaison Report

3.1 NA TC Chapter

3.2 Taiwan TC Chapter

4 Staff Report

5 Ballot Review

5.1 Cycle 8-2020 submitted by the Japan TC Chapter

5.1.1.1 6590 - New Standard: Specification for Glass Carrier Characteristics for Panel Level Packaging (PLP) Applications

6 Task Force & Study Group Reports

6.1 GCS

6.2 3D Packaging & Integration 5 Year Review Task Force

6.3 3DS IC Bonded Layer Inspection Metrology Task Force

6.4 450 mm Assembly & Test Die Preparation (ATDP) Task Force

6.5 Encapsulation Characteristics for Wafer Level Package and Panel Level Packaging Task Force

6.6 Panel Level Packaging (PLP) Glass Carrier Task Force

6.7 Thin Chip Handling Task Force

6.8 3D Packaging & Integration Steering Group

7 Old Business

7.1 Project Period Review

7.2 5 Year Review Check

8 New Business

8.1 Ballot Submission

8.2 Review of G13,G70,G75 and G95

9 Action Item Review

9.1 Open Action Items

9.2 New Action Items

10 Next Meeting and Adjournment